

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,495,326 B2
APPLICATION NO. : 10/689976
DATED : February 24, 2009
INVENTOR(S) : Rinne

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

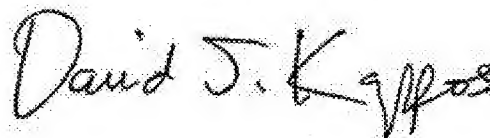
Column 9, Line 30: Please insert the following paragraph:

-- As shown in the cross section of Figure 5, a stack of substrates **10a-c** may be mounted on a substrate **210** (such as a printed circuit board PCB) on which conductors have been provided corresponding to the small solder bumps **40**, the conductive traces **30**, and the large solder bumps **50**. A signal path **60**, for example, may be provided from the substrate **210** through large bump **50a** into conductive trace **30a** along the device side of the substrate **10a** to small bump **40a**, and then down to a small pad **240** on the substrate **210** below, then across the face of the substrate **210** and up through the large bump **50b** of the second substrate **50b**. The signal may then traverse the device side (active face) of the second substrate **10b** through conductive trace **30b** and down through small bump **40b** into the small pad **140a** on the backside (inactive face) of the first substrate **10a**, and then through conductive trace **130a** to the large pad **150a** and up through the large bump **50c** of the third substrate **10c**. This zig-zag interconnection topology may continues up through a stack of any number of substrates **10**. --

Column 16, Claim 15, Line 8: Please correct "claim 13" to read -- claim 14 --

Column 20, Claim 36, Line 10: Please correct "claim 34" to read -- claim 35 --

Signed and Sealed this
Nineteenth Day of July, 2011

A handwritten signature in black ink that reads "David J. Kappos". The signature is written in a cursive, flowing style with a large initial "D".

David J. Kappos
Director of the United States Patent and Trademark Office